

Course name	ECE 30500 Semiconductor Devices
Credit and contact hours	(3 cr.) Class 3
Course coordinator's name	Peter Schubert
Textbook	Robert F. Pierret, <i>Semiconductor Device Fundamentals</i> , Prentice Hall, 1996. ISBN: 0-201-54393-1
Course information	<p>2020-21 IUPUI Campus Bulletin description:</p> <p>ECE 30500 Semiconductor Devices (3 cr.) P: ECE 25500, MATH 26600, and PHYS 25100. Class 3. Materials- and phenomena-based examination of devices, emphasizing the how and why of solid-state device operation.</p> <p>Prerequisites/ Co-Requisite P: ECE 25500, MATH 26200, PHYS 25100</p> <p>Required, Elective, or Selected Elective: EE Elective, CE Elective</p>
Goals for the course	<p>Upon successful completion of the course, students should be able to</p> <ol style="list-style-type: none"> 1. Solve problems of atom spacing for simple, bcc, fcc, and diamond structures. [1] 2. Determine the carrier distribution from the density of states and the Fermi function. [1] 3. Calculate minority and majority carriers from charge neutralization relationship and np product relationship. [1] 4. Describe the various carrier actions including diffusion, drift, recombination and generation. [1] 5. Model the semiconductor materials in energy band diagram and find physical meanings of potential difference and energy on the diagram. [1, 6] 6. Describe the various IC processes required for fabricating a device on a silicon wafer. [2] 7. Determine the electrostatic, dynamic, and transient performances of a PN junction. [1] 8. Construct the I-V characteristics of a P-N junction diode using diffusion and R-G center current components. [1] 9. Design a p-n junction for a given reverse saturation current. [2] 10. Determine the effect of high current, high frequency of the PN junction diode characteristics and parameters. [1] 11. Design photodiodes for high frequency operation using PiN, and compare between Avalanche Photodiodes with PiN in terms of S/N ratio. [1] 12. Determine the conditions on forming compound semiconductors of compound substrate materials that are suitable for LEDs. [1]

	<p>13. Determine the electrostatic, dynamic, and transient performances of a PNP/NPN BJTs. [1]</p> <p>14. Describe the physics behind base width modulation and punch-through. [1]</p> <p>15. Determine the effect of dc collector current on dc current gain of a BJT. [1]</p> <p>16. Explain and apply theories of the PNP device characteristics and means of their firing using SCS and UJT devices. [1, 6]</p> <p>17. Apply MS Schottky diodes to BJT for high speed operation to design of MOSFET. [1,6]</p> <p>18. Determine the dc and ac characteristics for JFET and MOSFET. [1]</p> <p>19. Obtain a general expression for the threshold voltage of a MOSFET device including ion implantation and body effect. [1]</p>
List of topics to be covered	<p>1. Semiconductor materials and models (2 classes)</p> <p>2. Carrier properties and statistics (3 classes)</p> <p>3. Carrier action: drift, diffusion and recombination-generation (5 classes)</p> <p>4. PN junction fabrication; electrostatics (3 classes)</p> <p>5. Ideal diode I-V characteristics (1 class)</p> <p>6. Derivation of ideal diode equation (3 classes)</p> <p>7. Deviations from ideal behavior: avalanche, Zener and tunnel diodes (1 class)</p> <p>8. Bipolar junction transistors (6 classes)</p> <p>9. Field effect transistors (2 classes)</p> <p>10. MOS structure, electrostatics (2 classes)</p> <p>11. MOSFET devices (2 classes)</p>
Syllabi approved by	Maher Rizkalla
Date of approval	04/10/2021